



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Patent Application of:)
DEANE ET AL) Atty Docket No.:
) 78153CIP1 (17-2 US
CIP1)
Serial No. 10/775,395)
) Art Group: 1725
Confirmation No. 8888)
)
Filing Date: FEBRUARY 10, 2004)
)
For: SOLDER BONDING TECHNIQUE FOR)
ASSEMBLING A TILTED CHIP)
OR SUBSTRATE)
)

TRANSMITTAL OF FORMAL DRAWINGS

Mail Stop Missing Parts
Commissioner of Patents
P.O. Box 1450
Alexandria, VA 22313-1450

Sir:

Enclosed are **Thirteen** (13) sheets of formal drawings to be filed in the above-identified patent application.

Respectfully submitted,

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